

ABSTRACT OF THE DISCLOSURE

A semiconductor package comprising multiple stacked substrates having flip chips attached to the substrates with chip-on-board assembly techniques to achieve dense packaging. The substrates are preferably stacked atop one another by electric connections which are column-like structures. The electric connections achieve electric communication between the stacked substrates, must be of sufficient height to give clearance for the components mounted on the substrates, and should preferably be sufficiently strong enough to give support between the stacked substrates.

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